samlec gEEk®spEEk

Mechanical Considerations for Compression Mount RF Connectors

Zak Speraw Samtec, Inc.

CURRENT & NEXT GEN CONNECTIVITY BOARD-TO-BOARD | SILICON-TO-SILICON





RF Compression Mount Connectors





For more information visit <u>www.samtec.com/precisionrf</u>

Swapping Out Solder for Screws





Impacts of Solder Reflow on High Bandwidth RF Connectors

samtec.com/geekspeek



Solderless Compression Mount High Bandwidth RF Connectors

<u>blog.samtec.com/post/</u> <u>what-is-an-rf-launch</u>

Compression Mount Challenges

Pin Protrudes ≈0.0025" to ensure contact with pad



Pin Compression into PCB

Blind Pin Alignment on PCB

Could the pin push into the PCB pad or dielectric? How can I verify alignment if I can't see the pin?

Pin should contact center of pad but visual confirmation is not possible

Compression Mount Challenges



Pin Compression into PCB



- 1. What is pin compression and what is the concern?
- 2. Can we accurately predict mechanical compression and what do we learn?
- 3. How do we convert a mechanical prediction into an electrical performance prediction?
- 4. What is the electrical impact of mechanical deformation and what can be done?

Potential Impact to Electrical Performance

Zak Speraw | Samtec, Inc.

What is Pin Compression and What is the Concern?









A hypothetical simulation was solved in HFSS to determine possible sensitivity of pin compression









Impedance continues to drop as pad is pressed into dielectric

This is a reasonable concern... But to what degree does this physically occur?





1. If pin compression occurs, it **COULD** negatively impact electrical performance

2. Does pin compression happen and can it be predicted?

Predicting Compression

Edwin Loy | Samtec, Inc.

Mounting Basics





Screws enter the opposite side of the PCB and tighten into the connector body to mount the connector in place

> Keep in mind that it's rotational torque which is translated into axial displacement, so this needs to be quantified

Ansys Mechanical Bolt Pretension





Exploration of Results



Exaggerated Deformation Display



Exaggerated Deformation Display of Trace



Nominal Deformation Display



Cross Section Image of Actual Trace



Correlation of Results



Nominal Deformation Display



Cross Section Image of Actual Trace





Simulation results agreed with physical images

0.6 in-lb. Case Results





Minimal Pin Compression and PCB Flex with nominal 0.6 in-lbs

Notable Results







Note that the simulation showed pin and bead displaced and flexed away from PCB respectively

Note the minimal deformation around the bolts as compared with the center pin

Copper Pad Deformation, Center Contact Displacement, and Bead Flexure all mitigate the risk of pin compression into the PCB

What If...

What if the screw was over tightened?



0.9 in-lb. Case Results





PCB WARPS before pad compresses!

What If...

What if the PCB material was softer?



PTFE Dielectric Results





PCB WARPS before pad compresses!

Below minimum torque!

Qualitative Correlation



• Similar product example of PCB warping with over-torque



 Side part contact is indicator of "over compression"



TIP: Inspect for board warpage by looking for board to body contact along the outer edges of the connector

Section Takeaways



- Mechanical Simulation agreed with physical images
- Pin compression was minimal with our PCB stack up and recommended torque
- Board warpage is a factor of concern, perhaps more than pin compression
- Recommend checking gaps for PCB warpage control

Preparing Mechanical Results for Electrical Simulation

Sage Wronowski | Samtec, Inc.

From Mechanical to HFSS





Notice the "faceted" segments

The goal is to convert the STL into something more suited for EM simulation **without removing deformed details**



Notice smooth without facets

What are STL Files and Why Should We Convert?



71,690 KB

The STL represents the surface mesh from mechanical simulation as a series of facets





is actually a 70 MB file!

Direct Conversion to Solid





Discovery "Fit Spline" Tool



Fit spline is then used

on the bottom of the

top layer to use as a cut

plane



Autoskin is used for the top, then the faces are thickened towards the bottom



File Size Comparison



• The resulting faceted, and splined files were saved as STEP files for import into HFSS



Deformed Connector Geometry



Mechanical simulation identified bead deformation, allowing pin to displace away from PCB pad





Extract Curves



Pull Tool



Solid Object created





Color coded fit compares deviation between original and "cleaned" geometry



Faceted Model vs "Cleaned" Model Comparison

5x Reduction File Size in "cleaned" model 5x Reduction Project Size in "cleaned" model 4x Reduction Solve Time in "cleaned" model **2x Reduction** Solve Memory in "cleaned" model

Note these differences are specific to this project and workflow

Section Takeaways

- Different cleanup methods offer varying degrees of cleanup success
- Potential electrical simulation errors can be avoided with geometry cleanup
- Geometry cleanup is critical for successful and efficient electrical simulation

Predicted Impact to Electrical Performance

Zak Speraw | Samtec, Inc.

Electrical Impact – 0.9 in-lbs of Torque

When the pin and pad are flush, the VSWR is optimal with nominal impedance

Standard 0.6 in-lbs torque did lift the impedance profile slightly but impact on VSWR was minimal

Over-torqued 0.9 in-lbs resulted in a larger impact on VSWR, particularly at higher frequencies

Electrical Impact of PCB Warpage

However, increased PCB warpage created a cavity between the connector and PCB

Electromagnetic leakage into any cavity can lead to electrical suckout and degrade performance

Section Takeaways

- 0.6 in-lbs of assembly torque showed minimal impact on electrical performance for this case
- Over-torquing increases risk of electrical performance degradation
- Warped PCBs can create a cavity and increase risk of electrical suck out

Blind Pin Alignment

Michael Griesi | Samtec, Inc.

Compression Mount Challenges

to ensure contact with pad

Pin Compression into PCB

Blind Pin Alignment on PCB

Could the pin push How can I verify into the PCB pad or alignment if I dielectric? can't see the pin? Pin should contact center of pad but visual Pin Protrudes ≈0.0025" confirmation is not possible

Compression Mount Challenges

- 1. What are the misalignment degrees of freedom?
- 2. What is the sensitivity of each degree of freedom?
- 3. How can we mitigate misalignment?

Pin should contact center of pad but visual confirmation is not possible

Blind Pin Alignment on PCB

How can I verify alignment if I can't see the pin?

Misalignment Degrees of Freedom

Side to Side

Back and Forth

Rotational

Side to Side Misalignment

Side to Side Misalignment

VSWR was not very sensitive to tangential misalignment

Back and Forth Misalignment

Back and Forth Misalignment

VSWR was very sensitive to back and forth misalignment

Rotational Misalignment

Rotational Misalignment

Prop Rotational Misalignment

VSWR was moderately sensitive to rotational misalignment

Precision RF Connector PCB Launches for 224 Gbps Devices

Microstrip versus Stripline

Microstrip has an inherent indicator to minimize side-to-side and rotational misalignment but not back-and-forth Stripline has no inherent indicator to aid with alignment and is therefore, entirely blind

The Solution to Pin Alignment

RF Compression Mount Alignment Indicator

Alignment Features

Exclusive to Samtec

Align Connector the First Time - Every Time

Section Takeaways

- Proper alignment is critical for reliable electrical performance
- Alignment features on connector can ensure proper alignment for reliable performance

Actual Performance

1.35mm Vertical Compression Mount Microstrip (CMM)

MEASURED PERFORMANCE

The results above used automatic fixture removal (AFR) on the measurement to isolate the connector and PCB launch on the top layer of a 6-layer Tachyon 100G.

135-CM/CMM

ELECTRICAL DATA

https://www.samtec.com/products/135

Impedance	50 Ohm
Frequency Range	DC to 90 GHz
VSWR ¹	DC to 40 GHz: 1.25:1 Max 40 GHz to 80 GHz: 1.55:1 Max 80 GHz to 90 GHz: 1.6:1 Max
Insertion Loss ²	0.03 √F (GHz) dB Max
Insulation Resistance	5000 MOhm Min
Voltage Rating (Sea Level)	170 Vrms Max
DWV	475 Vrms Min (sea level)
Torque (board mount)	0.5 ~ 0.8 in-lbs

¹VSWR per connector when tested on Samtec multi-layer test PCB ²Single connector insertion loss only

Conclusion

Mechanical pin compression can occur but PCB warpage might occur before pin compression

PCB warpage can lead to electrical suck outs

For maximum performance, follow the recommended mounting torque and visually inspect for warpage

For maximum performance, use RF Compression Mount Connectors with Alignment Features

gEEk spEEk

samtec.com/geekspeek

 \sim

geekspeek@samtec.com

SIG@samtec.com